

**EB1216JA10-27.000M TR** [Click part number to visit Part Number Details page](#)
**REGULATORY COMPLIANCE** (Data Sheet downloaded on Aug 16, 2018)

[Click badges to download compliance docs](#)

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**ITEM DESCRIPTION**

Automotive Grade Quartz Crystal Resonator 1.2mm x 1.6mm x 0.4mm 4 Pad Ceramic Surface Mount (SMD)  
27.000MHz  $\pm 15$ ppm at 25°C,  $\pm 30$ ppm over -40°C to +85°C 10pF Parallel Resonant


**ELECTRICAL SPECIFICATIONS**

|                               |  |
|-------------------------------|--|
| Nominal Frequency             | 27.000MHz  |
| Frequency Tolerance/Stability | $\pm 15$ ppm at 25°C, $\pm 30$ ppm over -40°C to +85°C |
| Aging at 25°C                 | $\pm 3$ ppm/year Maximum                               |
| Load Capacitance              | 10pF Parallel Resonant                                 |
| Shunt Capacitance             | 5pF Maximum  |
| Equivalent Series Resistance  | 150 Ohms Maximum                                       |
| Mode of Operation             | AT-Cut Fundamental                                     |
| Drive Level                   | 100 $\mu$ Watts Maximum                                |
| Spurious Response             | -3dB Minimum (Measured from Fo to Fo +5000ppm)         |
| Storage Temperature Range     | -50°C to +150°C  |
| Insulation Resistance         | 500 Megaohms Minimum (Measured at 100Vdc)              |

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

|                              |   |
|------------------------------|---|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A         |
| Flammability                 | UL94-V0                                       |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C         |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B         |
| Moisture Resistance          | MIL-STD-883, Method 1004                      |
| Moisture Sensitivity         | J-STD-020, MSL 1                              |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K          |
| Resistance to Solvents       | MIL-STD-202, Method 215                       |
| Solderability                | MIL-STD-883, Method 2003                      |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B         |
| Vibration                    | MIL-STD-883, Method 2007, Condition A         |

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION   |
|-----|--------------|
| 1   | Crystal      |
| 2   | Cover/Ground |
| 3   | Crystal      |
| 4   | No Connect   |

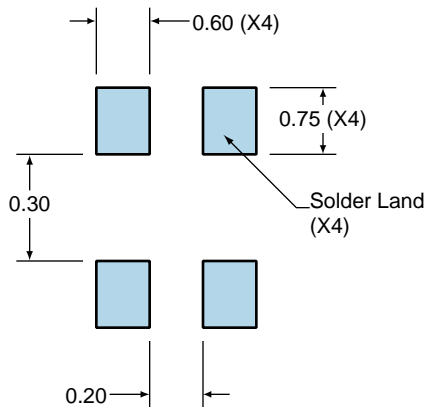
| LINE | MARKING  |
|------|--|
| 1    | <b>27.00</b>   |
| 2    | <b>XXX</b><br>XXX=Ecliptek<br>Manufacturing Identifier |

**Seam Sealed**

**Terminal Plating Thickness:** Gold (0.3 to 1.0 $\mu$ m) over Nickel (2.00 to 8.89 $\mu$ m).

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

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## Tape & Reel Dimensions

Quantity Per Reel: 3,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

|  |   |
|--|---|
| <b>Ts MAX to TL (Ramp-up Rate)</b>         | 3°C/Second Maximum                                |
| <b>Preheat</b>                             |   |
| - Temperature Minimum (Ts MIN)             | 150°C   |
| - Temperature Typical (Ts TYP)             | 175°C   |
| - Temperature Maximum (Ts MAX)             | 200°C   |
| - Time (ts MIN)                            | 60 - 180 Seconds                                  |
| <b>Ramp-up Rate (TL to TP)</b>             | 3°C/Second Maximum                                |
| <b>Time Maintained Above:</b>              |   |
| - Temperature (TL)                         | 217°C   |
| - Time (tL)                                | 60 - 150 Seconds                                  |
| <b>Peak Temperature (TP)</b>               | 260°C Maximum for 10 Seconds Maximum              |
| <b>Target Peak Temperature (TP Target)</b> | 250°C +0/-5°C                                     |
| <b>Time within 5°C of actual peak (tp)</b> | 20 - 40 Seconds                                   |
| <b>Ramp-down Rate</b>                      | 6°C/Second Maximum                                |
| <b>Time 25°C to Peak Temperature (t)</b>   | 8 Minutes Maximum                                 |
| <b>Moisture Sensitivity Level</b>          | Level 1   |
| <b>Additional Notes</b>                    | Temperatures shown are applied to body of device. |

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

|  |  |
|--|--|
| <b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b> | 5°C/Second Maximum                                     |
| <b>Preheat</b>   |  |
| - Temperature Minimum ( $T_S$ MIN)                             | N/A  |
| - Temperature Typical ( $T_S$ TYP)                             | 150°C  |
| - Temperature Maximum ( $T_S$ MAX)                             | N/A  |
| - Time ( $t_s$ MIN)  | 30 - 60 Seconds  |
| <b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>     | 5°C/Second Maximum                                     |
| <b>Time Maintained Above:</b>                                  |  |
| - Temperature ( $T_L$ )  | 150°C  |
| - Time ( $t_L$ )   | 200 Seconds Maximum                                    |
| <b>Peak Temperature (<math>T_P</math>)</b>                     | 245°C Maximum  |
| <b>Target Peak Temperature (<math>T_P</math> Target)</b>       | 245°C Maximum 2 Times / 230°C Maximum 1 Time           |
| <b>Time within 5°C of actual peak (<math>t_p</math>)</b>       | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>  | 5°C/Second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>                       | N/A  |
| <b>Moisture Sensitivity Level</b>                              | Level 1  |
| <b>Additional Notes</b>  | Temperatures shown are applied to body of device.      |

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)